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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	Lary R. Larson	Group Art Unit:	1765
Application No.:	09/735,826	Examiner:	L. Umez Eronini
Filing Date:	December 13, 2000		
For:	METHOD FOR STACKING SEMICONDUCTOR DIE WITHIN AN IMPLANTED MEDICAL DEVICE		

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6/27/03

PRELIMINARY AMENDMENT

Mail Stop RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Please enter this Preliminary Amendment before the calculation of filing fees.

IN THE CLAIMS:

1. (Previously cancelled) A method for forming a stackable wafer in an implantable device, comprising:

- forming an opening extending substantially through the wafer;
- depositing conductive material within the opening to substantially fill the opening;
- forming a bump on an upper surface of the wafer adjacent the conductive material; and
- forming a contact pad on a lower surface of the wafer adjacent the conductive material.

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